
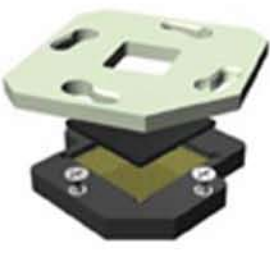
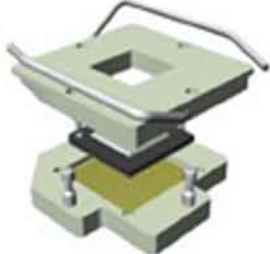
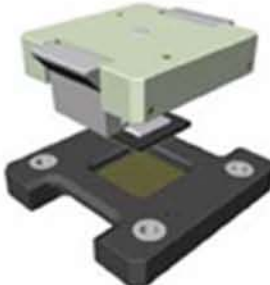




## A Patented IC Development Socket System

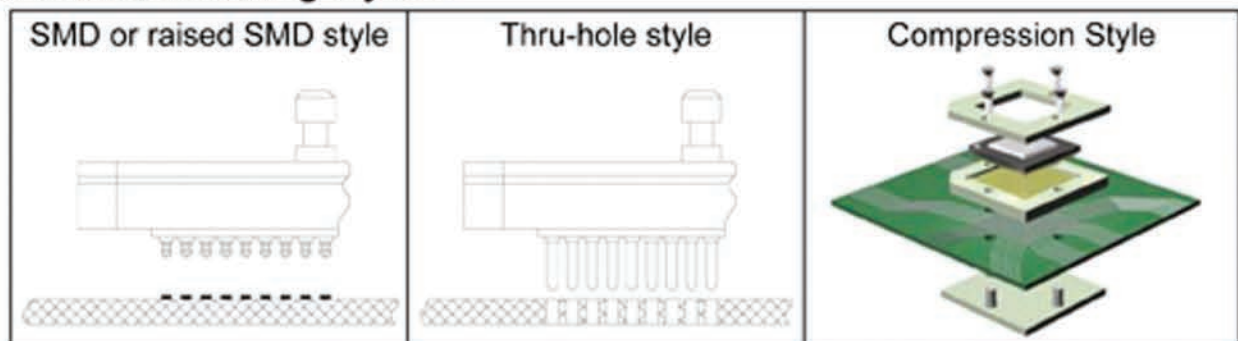
### Features:

- -1dB bandwidth: >14GHz for compression style; 3GHz for SMD style
- Inductance: less than 2nH
- Any package style: ceramic & plastic BGA, CSP, LGA, CGA, PSGA, MLF/QFN, QFP, SOIC, and other standard packages, custom packages or bare die
- Lead pitch: >0.30mm for compression style;  $\geq 0.5$ mm for SMD or thru-hole styles
- Any pin count and grid
- Contact force: max 40 grams per contact; lower forces available
- Same PCB layout as the IC (no holes required for SMD socket)
- Minimal keepout area of 6mm beyond the IC's periphery
- Raised SMD style for lifting socket over adjacent components
- Thermal expansion, shock & vibration absorbed by contact design
- Low profile socket (standard Twist Lock is less than 10mm high with IC)
- Heat dissipation with open frame or integrated heatsink
- Open frame designs suitable for failure analysis or optical IC development
- ESD dissipative material
- Semi-custom design = lower cost and tailored to your needs
- Available 5, 7, 10 or 15-day rush service; 5-week standard delivery ARO

### Available Retention Systems :

<p>"Knob lock" for multiple insertions and extractions of chips, for example in test and burn-in</p> 	<p>"Twist lock" for prototypes and pre-production</p> 	<p>"Lever lock" for pre-production and volume productions</p> 
<p>"Quick lock" for test purposes (socket up to 80 pins)</p> 	<p>"Quick lock" for test purposes (socket as of 81 pins)</p> 	<p>"Clamshell" for test purposes</p> 
<p>Please contact ET for other socket styles or custom specials</p>		

### Available Mounting Styles :



## Production BGA Socket: HiLo Flexible Interconnect System

### Highs:

High Density: 0.8mm pitch and above

High Speed: 1dB cut-off measured at 9.3GHz

High Reliability: Proven dual-beam gold plated beryllium copper contacts

High I/O: Over 2,000 I/O

High Speed Assembly: Pick and place compatible

### Lows:

Low Profile: Socket height less than 2mm

Low Cost: As low as \$0.02/contact in high volume

Low Insertion Force: 1.0 oz per contact

Low Tooling Cost: Tooling cost for custom footprints less than \$1,000



## Emulation Technology

ET is celebrating its 26<sup>th</sup> year of providing quality interconnect solutions for design and development engineers. The company's experience helping engineers create quality products and reducing costs associated with design, development, and time to market has made it the leader in this industry. Emulation Technology has more than 50,000 customers and operations in 23 countries worldwide. The company is privately held and is headquartered in Santa Clara, California. Contact us today and let our courteous, experienced and knowledgeable staff provide a solution to your socket needs.